



# ETU-LINK

Optical Communication System

## SFP28 Series

### SFP28

#### ES2312X-3LCD10

#### 25Gbps 1310nm 10KM SFP28 Transceiver

- Hot-pluggable SFP28 form factor
- Supports 25Gbps data rate
- Maximum link length of 10km
- 1310nm DFB laser and PIN photo-detector
- Internal CDR on both Transmitter and Receiver channel
- Duplex LC receptacle
- Single 3.3V power supply
- Power dissipation < 1.5W
- Digital diagnostics functions are available via the I2C interface
- RoHS-6 compliant
- Commercial case temperature range: 0°C to 70°C



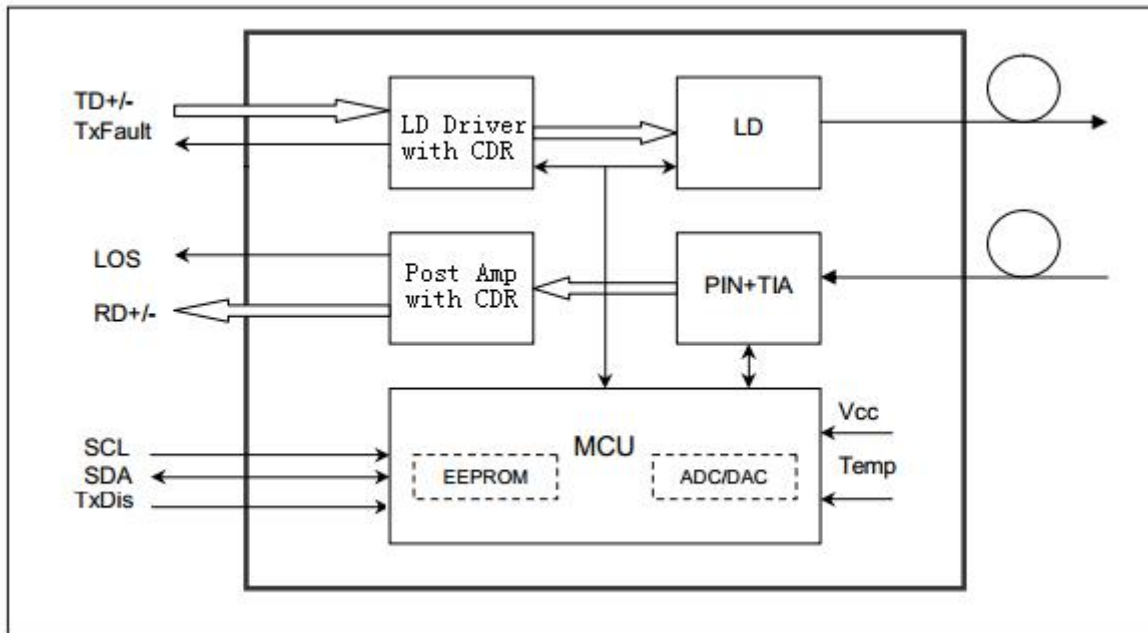
### Applications

- 25GBASE-LR Ethernet

### Description

The ES2312X-3LCD10 is a single-Channel, Pluggable, Fiber-Optic SFP28 for 25 Gigabit Ethernet and Infiniband EDR Applications. It is a high performance module for short-range data communication and interconnect applications which operate at 25.78125 Gbps up to 10km. This module is designed to operate over single mode fiber systems using a nominal wavelength of 1310nm. The electrical interface uses a 20 contact edge type connector. The optical interface uses duplex LC receptacle. This module incorporates proven circuit and technology to provide reliable long life, high performance, and consistent service.

## Block Diagram



## Absolute Maximum Ratings

Table1 - Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply Voltage	Vcc	0	3.6	V
Storage Temperature	Ts	-40	+85	°C
Operating Humidity	-	5	85	%

## Recommended Operating Conditions

Table2 - Recommended Operating Conditions

Parameter	Symbol	Min	Typical	Max	Unit
Operating Case Temperature	Tc	0		+70	°C
Power Supply Voltage	Vcc	3.13	3.3	3.47	V
Power Supply Current	Icc			450	mA

## Optical and Electrical Characteristics

**Table 3 - Optical and Electrical Characteristics**

Parameter	Symbol	Min	Typical	Max	Unit	Notes
<b>Transmitter</b>						
Data rate	BR		25.78		Gbps	
Centre Wavelength	$\lambda_c$	1290	1310	1330	nm	
Spectral Width (-20dB)	$\sigma$			1	nm	
Side Mode Suppression Ratio	SMSR	30			dB	
Average Output Power	Pavg	2		3	dBm	
Extinction Ratio	ER	4.0			dB	
Differential data input swing	V <sub>IN,PP</sub>	180		700	mV	
Input Differential Impedance	Z <sub>IN</sub>	90	100	110	$\Omega$	
TX Disable	Disable	2.0		V <sub>cc</sub>	V	
	Enable	0		0.8	V	
TX Fault	Fault	2.0		V <sub>cc</sub>	V	
	Normal	0		0.8	V	
<b>Receiver</b>						
Data rate	BR		25.78		Gbps	
Centre Wavelength	$\lambda_c$	1260	1310	1360	nm	
Receiver Sensitivity (OMA)	P <sub>sens</sub>	-	-	-11.5	dBm	
Stressed Sensitivity (OMA)		-	-	-6.8	dBm	
LOS De-Assert	LOS <sub>D</sub>			-12.5	dBm	
LOS Assert	LOS <sub>A</sub>			-13.5	dBm	
LOS Hysteresis		0.5			dB	
Differential data output swing	V <sub>out,PP</sub>	300		900	mV	
LOS	High	2.0		V <sub>cc</sub>	V	
	Low			0.8	V	

**Notes:**

## Timing and Electrical

Table 4 - Timing and Electrical

Parameter	Symbol	Min.	Max.	Unit	Conditions
Tx_Disable assert time	t_off		100	μs	Rising edge of Tx_Disable to fall of output signal below 10% of nominal
Tx_Disable negate time	t_on		2	ms	Falling edge of Tx_Disable to rise of output signal above 90% of nominal. This only applies in normal operation, not during start up or fault recovery.
Time to initialize 2-wire interface	t_2w_start_up		300	ms	From power on or hot plug after the supply meeting Table 8.
Time to initialize	t_start_up		300	ms	From power supplies meeting Table 8 or hot plug or Tx disable negated during power up, or Tx_Fault recovery, until non-cooled power level I part (or non-cooled power level II part already enabled at power level II for Tx_Fault recovery) is fully operational.
Time to initialize cooled module and time to power up a cooled module to Power Level II	t_start_up_cooled		90	s	From power supplies meeting Table 8 or hot plug, or Tx disable negated during power up or Tx_Fault recovery, until cooled power level I part (or cooled power level II part during fault recovery) is fully operational. Also, from stop bit low-to-high SDA transition enabling Power Level II until cooled module is fully operational
Time to Power Up to Level II	t_power_level2		300	ms	From stop bit low-to-high SDA transition enabling power level II until non-cooled module is fully operational
Time to Power Down from Level II	t_power_down		300	ms	From stop bit low-to-high SDA transition disabling power level II until module is within power level I requirements
Tx_Fault assert	Tx_Fault_on		1	ms	From occurrence of fault to assertion of Tx_Fault
Tx_Fault assert for cooled module	Tx_Fault_on_cooled		50	ms	From occurrence of fault to assertion of Tx_Fault
Tx_Fault Reset	t_reset	10		μs	Time Tx_Disable must be held high to reset Tx_Fault
RS0, RS1 rate select timing for FC	t_RS0_FC, t_RS1_FC		500	μs	From assertion till stable output
RS0, RS1 rate select timing non FC	t_RS0, t_RS1		24	ms	From assertion till stable output
Rx_LOS assert delay	t_los_on		100	μs	From occurrence of loss of signal to assertion of Rx_LOS
Rx_LOS negate delay	t_los_off		100	μs	From occurrence of presence of signal to negation of Rx_LOS

## Diagnostics

Table5 – Diagnostics Specification

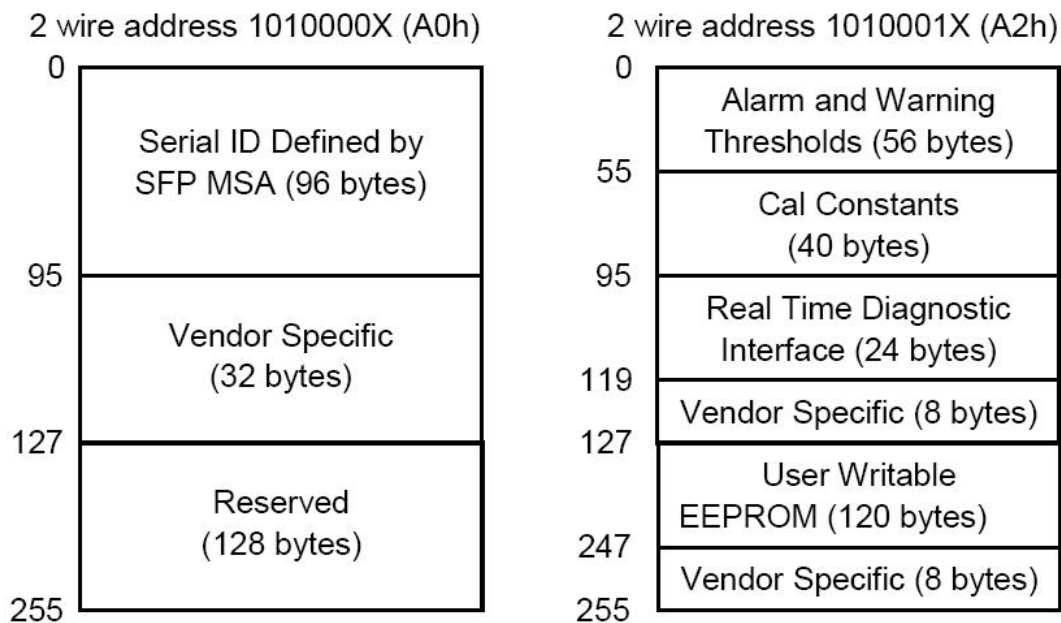
Parameter	Range	Unit	Accuracy	Calibration
Temperature	0 to +70	°C	±3°C	Internal / External
Voltage	3.0 to 3.6	V	±3%	Internal / External
Bias Current	0 to 100	mA	±10%	Internal / External
TX Power	-8 to 3	dBm	±3dB	Internal / External
RX Power	-14 to 0	dBm	±3dB	Internal / External

## Digital Diagnostic Memory Map

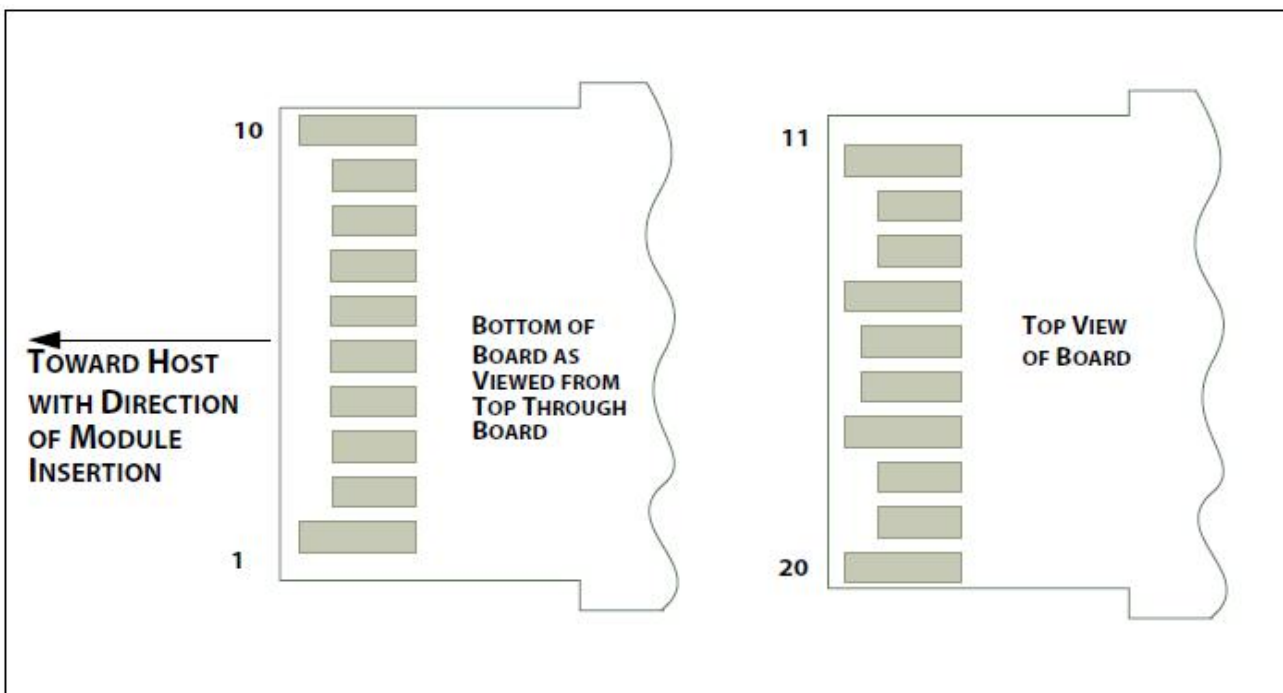
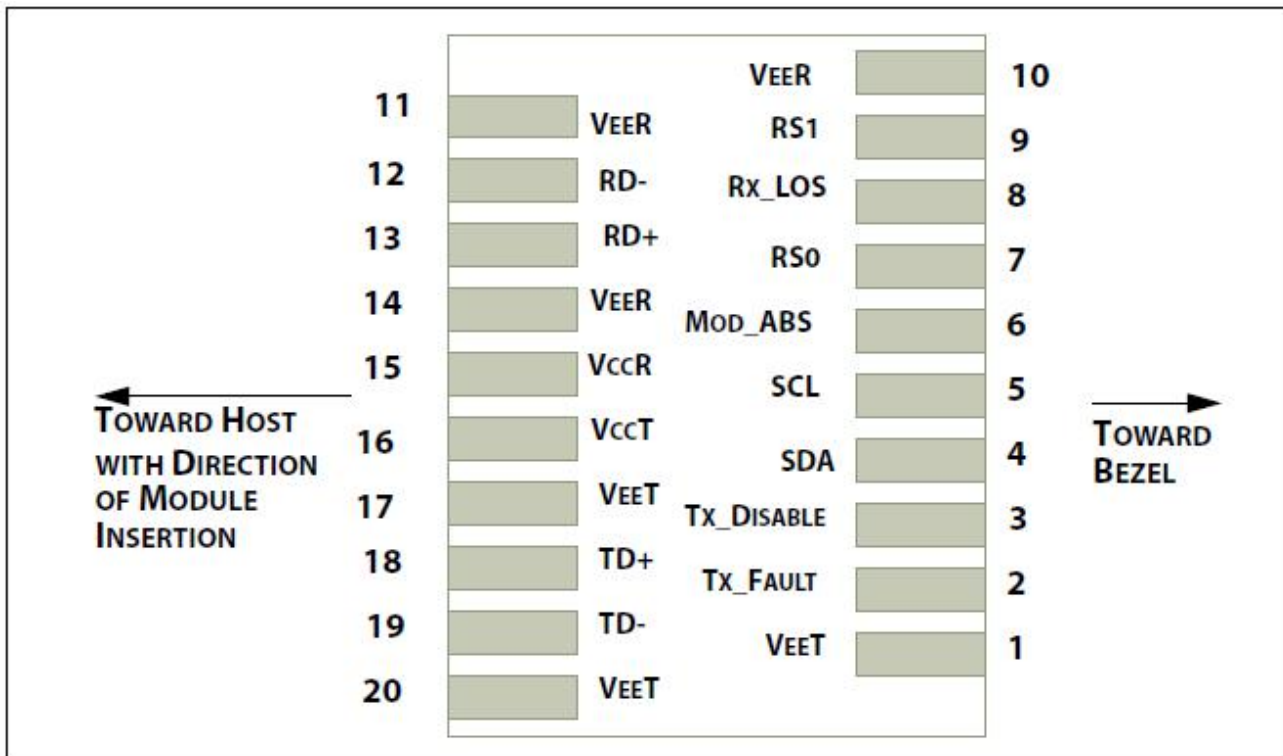
The transceivers provide serial ID memory contents and diagnostic information about the present operating conditions by the 2-wire serial interface (SCL, SDA).

The diagnostic information with internal calibration or external calibration all are implemented, including received power monitoring, transmitted power monitoring, bias current monitoring, supply voltage monitoring and temperature monitoring.

The digital diagnostic memory map specific data field defines as following.



## Pin Definitions



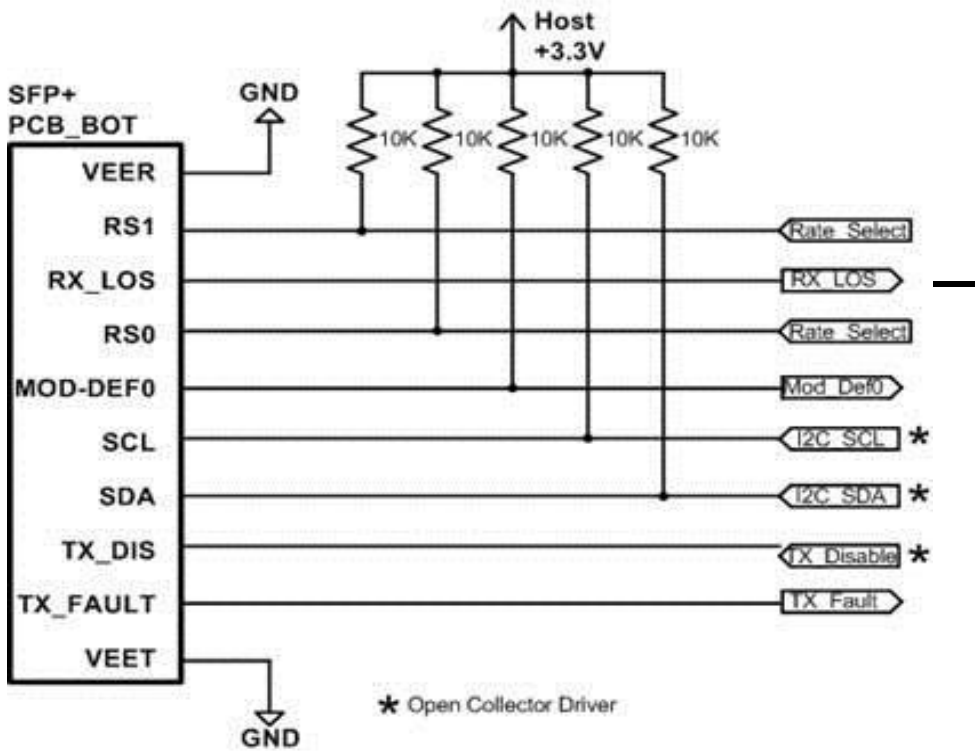
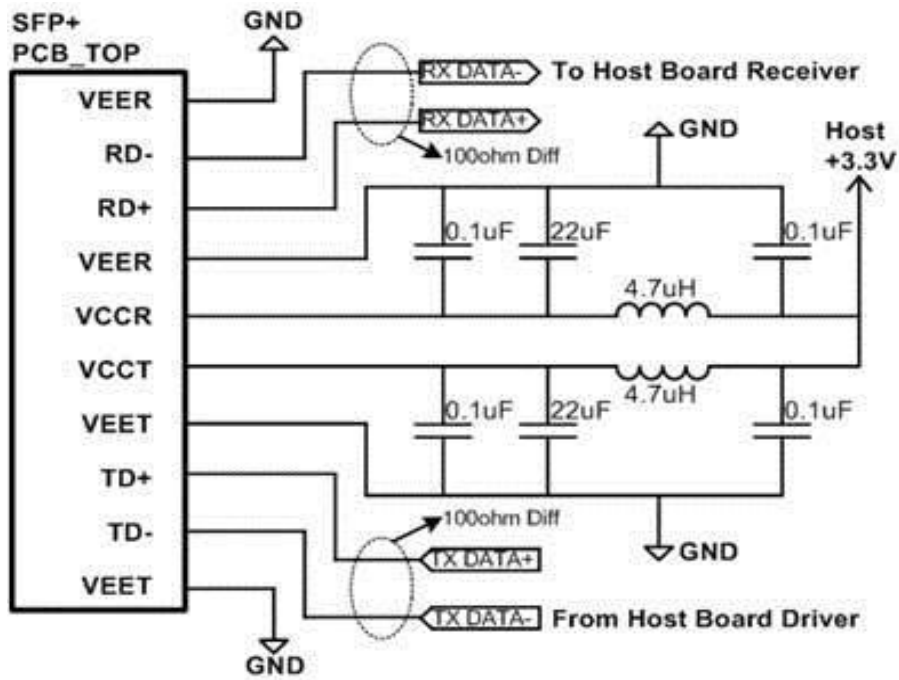
## Pin Descriptions

PIN	Logic	Symbol	Name / Description	Note
1		VeeT	Module Transmitter Ground	1
2	LVTTL-O	TX_Fault	Module Transmitter Fault	2
3	LVTTL-I	TX_Dis	Transmitter Disable; Turns off transmitter laser output	
4	LVTTL-I/O	SDA	2-Wire Serial Interface Data Line	2
5	LVTTL-I	SCL	2-Wire Serial Interface Clock	2
6		MOD_ABS	Module Definition, Grounded in the module	
7	LVTTL-I	RS0	Receiver Rate Select	
8	LVTTL-O	RX_LOS	Receiver Loss of Signal Indication Active LOW	
9	LVTTL-I	RS1	Transmitter Rate Select (not used)	
10		VeeR	Module Receiver Ground	1
11		VeeR	Module Receiver Ground	1
12	CML-O	RD-	Receiver Inverted Data Output	
13	CML-O	RD+	Receiver Data Output	
14		VeeR	Module Receiver Ground	1
15		VccR	Module Receiver 3.3 V Supply	
16		VccT	Module Receiver 3.3 V Supply	
17		VeeT	Module Transmitter Ground	1
18	CML-I	TD+	Transmitter Non-Inverted Data Input	
19	CML-I	TD-	Transmitter Inverted Data Input	
20		VeeT	Module Transmitter Ground	1

### Notes:

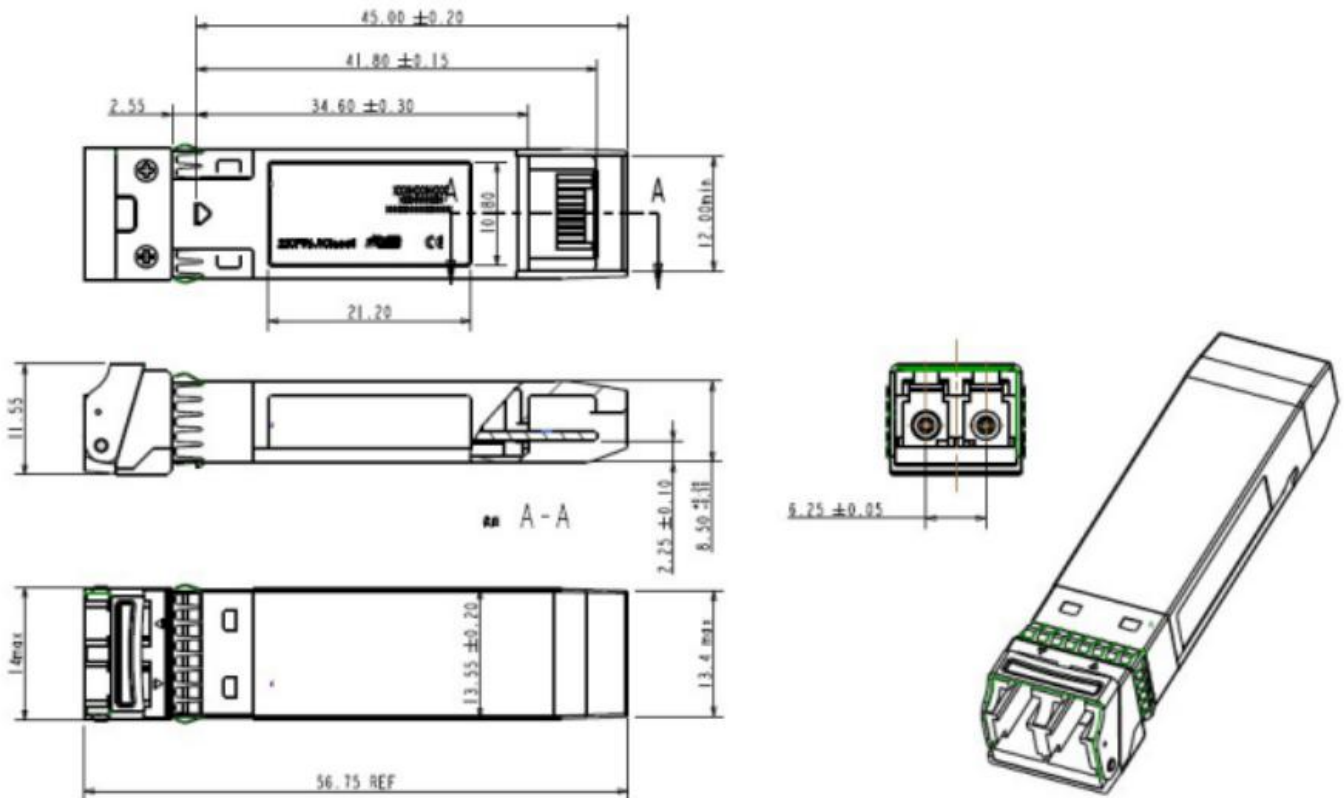
1. Module ground pins GND are isolated from the module case.
2. Shall be pulled up with 4.7K-10Kohms to a voltage between 3.15V and 3.45V on the host board.

## Recommended Interface Circuit





## Mechanical Dimensions



## Ordering information

Part Number	Product Description
ESP312A-3LCD10	25Gbps, 1310nm; SFP28, 10km, DDM 0°C ~ +70°C

## Compatibility Test

In order to ensure the product compatibility, our products will be tested on the switch before shipment. Our modules can compatible with many mainstream brand switches, such as Cisco, Juniper, Extreme, Brocade, IBM, H3C, HP, Huawei, D-Link, Mikrotik, ZTE, TP-Link...

Our test equipment: VOLKTEK MEN-4110, HP 2530-8G, CRS226-24G-25+RM, Catalyst 2960G Series, Catalyst 3850 XS 10G SFP+, Catalyst 3750-E Series, HUAWEI S5700Series, H3C S3100V2 Series, Juniper-EX4200, etc.



**Cisco Catalyst 3850**



**HUAWEI S5700**



**H3C S3100V2**



**HP J9264AR**



**Juniper EX 4200**



**Alcatel 6850E-U24X**



**Mikrotik CR5226-24G-25+RM**



**Cisco Catalyst 2960G**



**Volktek MEN-4110**

## Product Production Process

# Quality Assurance

Continuous introduction of new equipment, produced by strict standards, strict quality inspection, to guarantee the high quality standard of each product.



**Standardized  
Production Line**



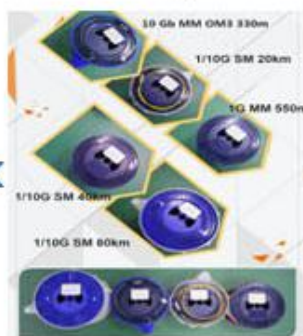
**Professional  
Welding**



**Assembling**



**Aging Testing**



**Distance Testing**



**Cleaning end face**



**Product Initial Test**



**Switch Testing**



**Product Final Test**



## Packaging

ETU-Link provides two kinds of packaging, 10pcs/Tray and individual package.



Company: ETU-Link Technology Co., LTD

Address: 4th Floor, C Building, JinBoLong Industrial Park, QingQuan Road, LongHua District, Shenzhen city, GuangDong

Tel: +86-755 2328 4603

Addresses and phone number also have been listed at [www.etulinktechnology.com](http://www.etulinktechnology.com).

Please e-mail us at [sales@etulinktechnology.com](mailto:sales@etulinktechnology.com) or call us for assistance.